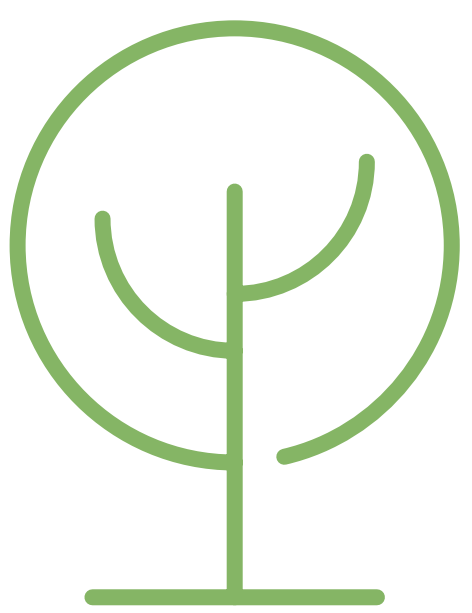
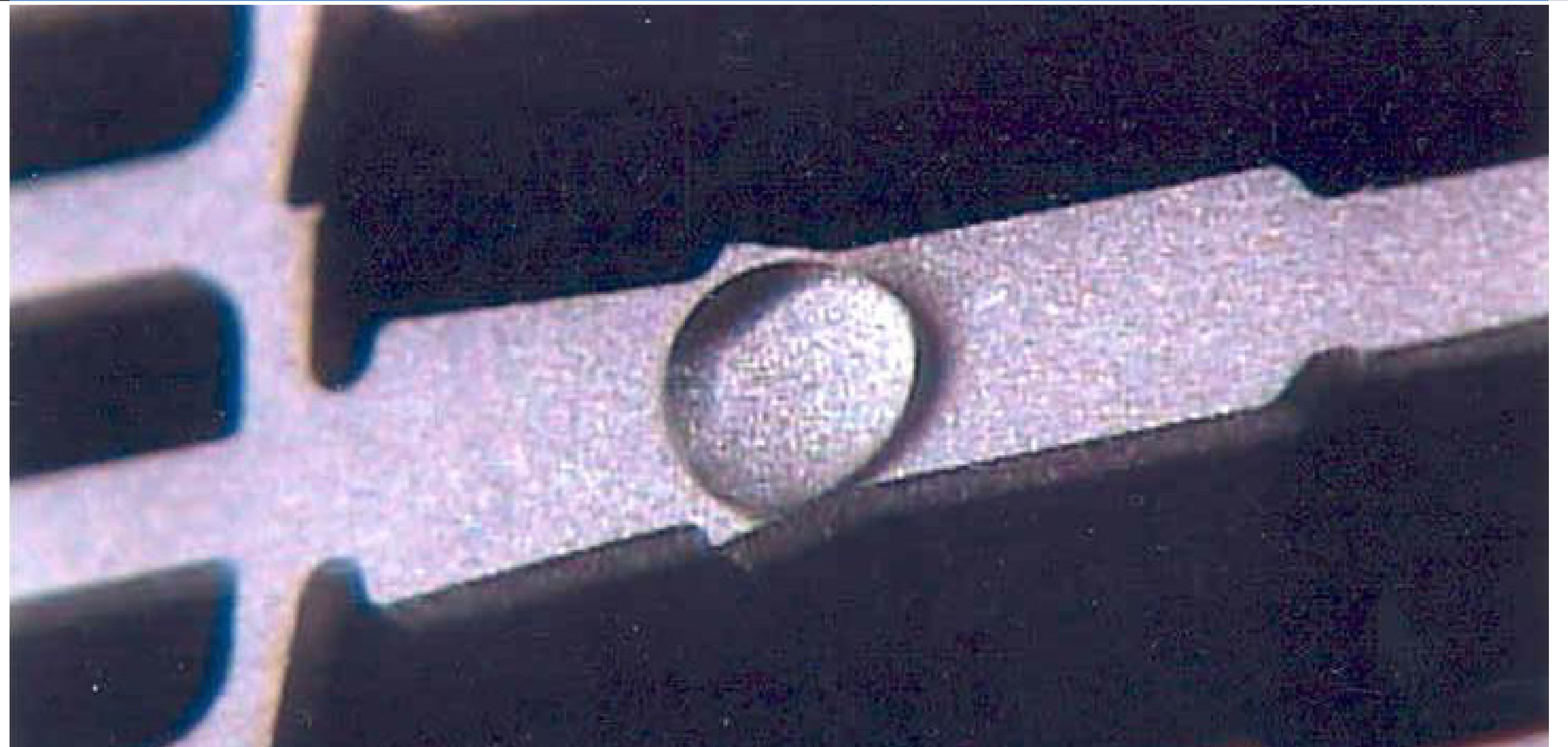


A sustainable post-treatment
to mitigate the corrosion
whisker formation

Protectostan® LF-E creates a hydrophobic surface



Free of BPA, NPE & PFAS



Highly solderable and highly effective

Protectostan® LF-E protects the plated tin and tin alloy surfaces of connectors and integrated circuits (ICs) from discoloration during heat and humidity storage conditions. Electronic components remain solderable even after long-term storage.

Protectostan® LF-E mitigates corrosion whisker formation. Its hydrophobic coating protects the plated tin surfaces from corrosion, thus reducing the excessive formation of corrosion whiskers. Protectostan® LF-E can easily replace alkaline tin post-treatments and be integrated into existing plating lines.

Protectostan® LF-E is the sustainable alternative to our established Protectostan® LF series and is free of any BPA, NPE & PFAS and other critical substances.

Features and benefits

- Sustainable alternative to our Protectostan® LF series
- Effective corrosion protection for plated tin and tin alloy surface finishes on IC outer leads
- Strongly mitigates the formation of whiskers during heat and humidity to comply with the iNEMI / Jedec storage condition (4,000 h at 55 °C / 85% RH)
- Prevents tarnishing during hot and humid storage conditions
- Excellent wettability and solderability after steam ageing and pressure cooker test conditions